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# STTH6102TV

## HIGH EFFICIENCY ULTRAFAST DIODE

#### MAIN PRODUCT CHARACTERISTICS

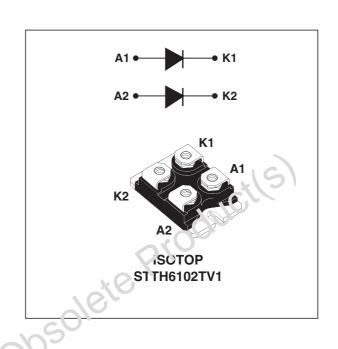
I <sub>F(AV)</sub>	2 x 30 A
V <sub>RRM</sub>	200 V
Tj (max)	150 °C
V <sub>F</sub> (typ)	0.70 V
t <sub>rr</sub> (typ)	25 ns

#### **FEATURES AND BENEFITS**

- Suited for welding and high power equipment
- Very low forward losses
- Low recovery times
- High surge current capability
- Insulated: Insulating voltage = 2500 V<sub>RMS</sub> Capacitance < 45 pF</li>
- Low leakage current



Dual center tap rectifier suited for welding equipment and high power industrial application. Packaged in ISOTOP, this device is intended for use in the secondary rectification of ocwer converters.



## ABSOLUTE RATINGS (limiting values, per diode)

ADOCEOTE TIATINGO (IIIII III) values, per diode)								
Symbol	Parameter				Unit			
V <sub>RRM</sub>	Repetitiv∈ peak reverse voltage			200	V			
I <sub>F(RMS)</sub>	FMS torward current Per diode				Α			
I <sub>F</sub> (AV)	Average forward current $\delta = 0.5$	Per diode	30	Α				
<b>J</b> FSM	Surge non repetitive forward current tp = 10 ms Sinusoidal per diode			400	Α			
T <sub>stg</sub>	Storage temperature range				°C			
Tj	Maximum operating junction temperature				°C			

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#### **THERMAL PARAMETERS**

Symbol	Parameter	Maximum	Unit	
R <sub>th (j-c)</sub>	Junction to case	Per diode	1.2	°C/W
		Per device	0.65	
R <sub>th (j-c)</sub>	Coupling		0.1	°C/W

When the diodes 1 and 2 are used simultaneously:

 $\Delta$  Tj (diode1) = P(diode1) x R<sub>th(j-c)</sub> (per diode) + P(diode2) x R<sub>th(c)</sub>

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests co	Min.	Typ.	Max.	Unit	
I <sub>R</sub> *	Reverse leakage	Tj = 25°C	$V_R = V_{RRM}$			50	μΑ
current		Tj = 125°C			25	250	
V <sub>F</sub> **	Forward voltage drop	Tj = 25°C	I <sub>F</sub> = 30 A			1.05	V
		Tj = 25°C	I <sub>F</sub> = 60 A			1.15	
		Tj = 150°C	I <sub>F</sub> = 30 A		0.70	0.81	
		Tj = 150°C	T <sub>F</sub> = 60 A			0.96	

Pulse test: \* tp = 5ms,  $\delta$  < 2%

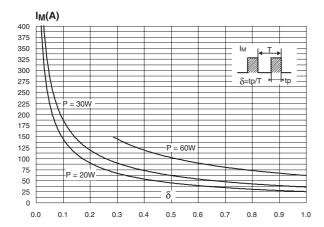
To evaluate the maximum conduction losses use the following equation : P = 0.66 x  $I_{F(AV)}$  + 0.005  $I_F^{\,2}({\rm RMS})$ 

### **DYNAMIC ELECTRICAL CHARACTERISTICS**

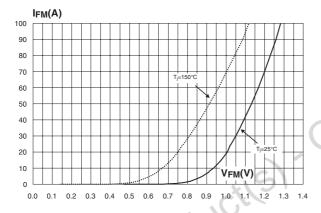
Symbol	Parameter	Tests conditions			Тур.	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	Tj = 25°C	$I_F = 1 A V_R = 30V$ $dI_F/dt = 200 A/\mu s$		25	30	ns
I <sub>RM</sub>	Reverse recovery current	Tj = 125°C	$I_F = 30 \text{ A } V_R = 160V$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$		6.8	8.8	Α
t <sub>fr</sub>	Forward recovery time	Tj = 25°C	$I_F = 30 \text{ A} \ dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_{FR} = 1.1 \text{ x V}_F\text{max}$			220	ns
V <sub>FP</sub>	Forward recovery voltage	Tj = 25°C	$I_F = 30 \text{ A} $ $dI_F/dt = 200 \text{ A/µs}$		2.5		V

<sup>\*\*</sup> tp = 380 $\mu$ s,  $\delta$  < 2%

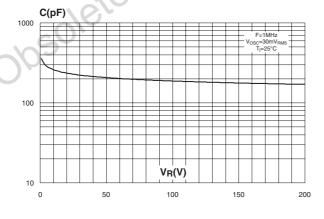
Fig. 1: Peak current versus duty cycle (per diode).



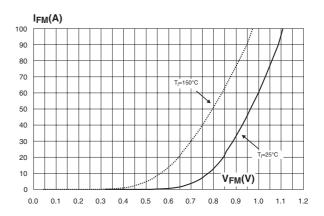
**Fig. 2-2:** Forward voltage drop versus forward current (maximum values, per diode).



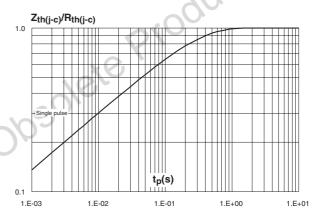
**Fig. 4:** Junction capacitance versus reverse voltage applied (typical values, per diode).



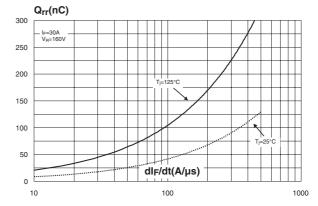
**Fig. 2-1:** Forward voltage drop versus forward current (typical values, per diode).



**Fig. 3:** Relative variation of thermal impedance junction to case versus pulse duration.

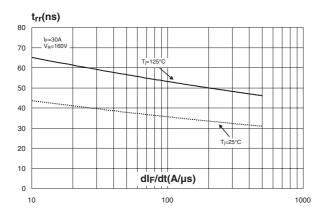


**Fig. 5:** Reverse recovery charges versus dI<sub>F</sub>/dt (typical values, per diode).

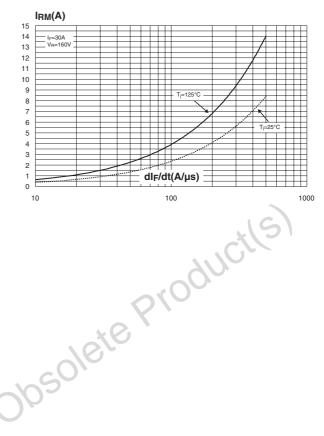


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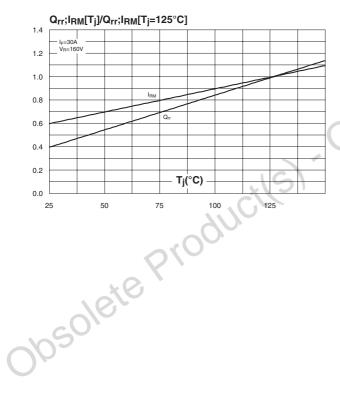
Fig. 6: Reverse recovery time versus  $dI_F/dt$  (typical values, per diode).



**Fig. 7:** Peak reverse recovery current versus  $dI_F/dt$  (typical values, per diode).



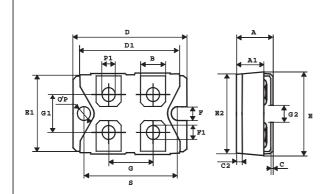
**Fig. 8:** Dynamic parameters versus junction temperature.



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## PACKAGE MECHANICAL DATA

**ISOTOP** 



	DIMENSIONS				
REF.	Millim	neters	Inches		
	Min. Max.		Min.	Max.	
Α	11.80	12.20	0.465	0.480	
A1	8.90	9.10	0.350	0.358	
В	7.8	8.20	0.307	0.323	
С	0.75	0.85	0.030	0.033	
C2	1.95	2.05	0.077	0.081	
D	37.80	38.20	1.488	1.504	
D1	31.50	31.70	1.240	1.248	
E	25.15	25.50	0.990	1.004	
E1	23.85	24.15	0.939	0.951	
E2	24.80	typ.	0.97	6 typ.	
G	14.90	15.10	0.587	0.594	
G1	12.60	12.80	0.496	0.504	
G2	3.50	4.30	0.138	0.169	
F	4.10	4.30	0.161	0.169	
F1	4.60	5.00	0.181	0.197	
Р	4.00	4.30	4.30 0.157 0.		

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
STTH6102TV1	STTH6102TV1	ISOTOP	27 g	10	Tube
	1,10		(without screws)	(with screws)	
olete	, COO.				

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